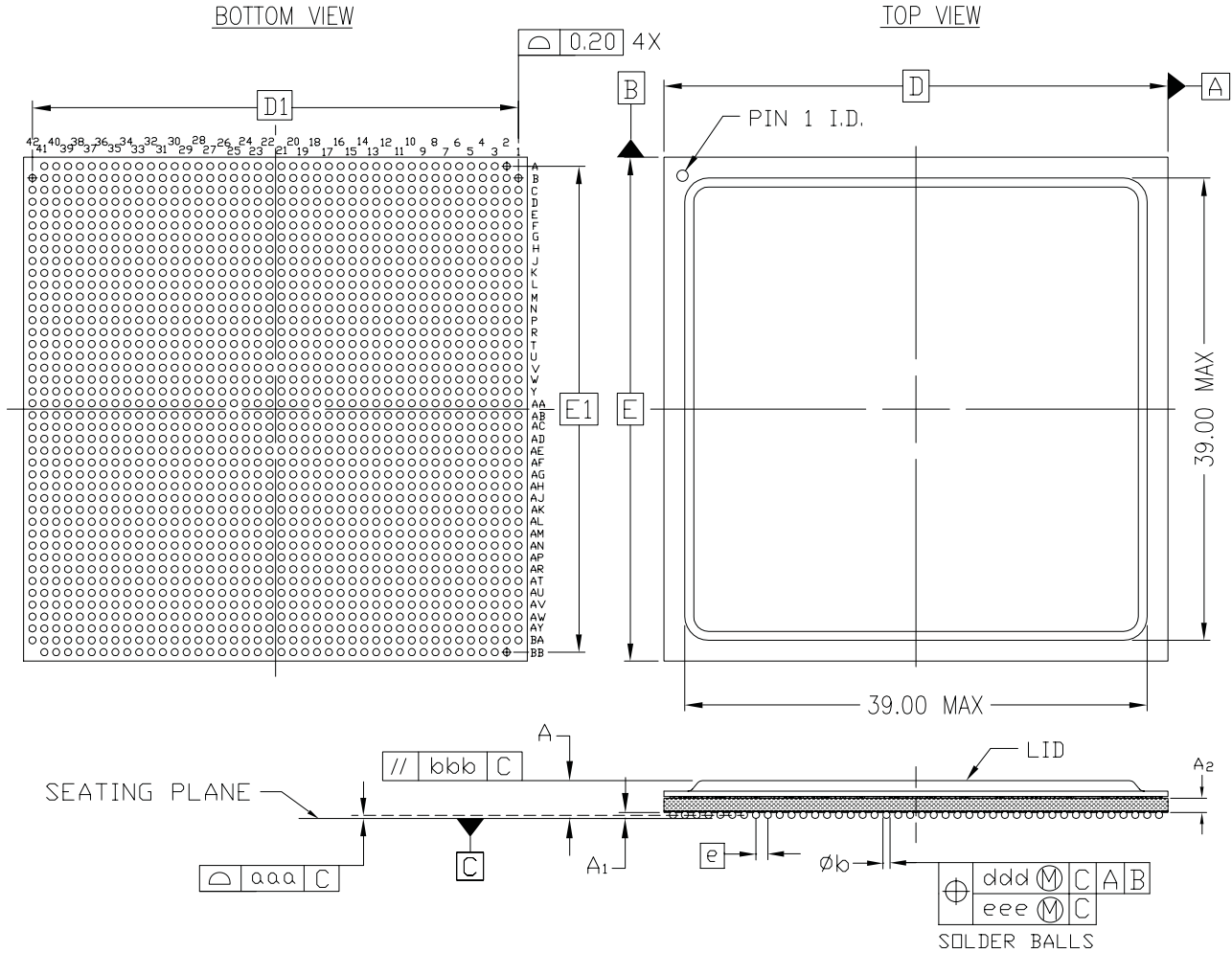


Flip-Chip BGA (FF1760) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	\approx	\approx	3.50	
A ₁	0.40	0.50	0.60	
A ₂	\approx	\approx	1.50	
D/E	42.50 BASIC			
D ₁ /E ₁	41.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
bbb	\approx	\approx	0.25	
ddd	\approx	\approx	0.25	
eee	\approx	\approx	0.10	
M	42			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAV-1 (DEPOPULATED)

1760-BALL FLIP-CHIP BGA (FF1760)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
9/13/04	1.0	Initial Xilinx release.
4/13/06	1.1	Revised from a "flat" lid to a "hat" type lid.